Obsolete Devices: TPS77127, TPS77201, TPS77215, TPS77218

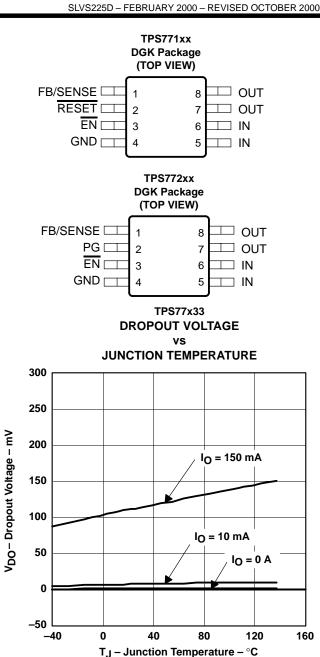
TPS77101/115/118/127/128/133/150 WITH RESET OUTPUT TPS77201/215/218/227/228/233/250 WITH POWER GOOD OUTPUT 150-mA LDO REGULATORS WITH 8-PIN MSOP PACKAGING

- Open Drain Power-On Reset With 220-ms Delay (TPS771xx)
- Open Drain Power-Good (PG) Status Output (TPS772xx)
- 150-mA Low-Dropout Voltage Regulator
- Available in 1.5-V, 1.8-V, 2.7-V, 2.8-V, 3.3-V, 5.0-V Fixed Output and Adjustable Versions
- Dropout Voltage Typically 115 mV at 150 mA (TPS77133, TPS77233)
- Ultralow 92-µA Quiescent Current (Typ)
- 8-Pin MSOP (DGK) Package
- Low Noise (55 μV_{rms}) Without External Filter (Bypass) Capacitor (TPS77118, TPS77218)
- 2% Tolerance Over Specified Conditions for Fixed-Output Versions
- Fast Transient Response
- Thermal Shutdown Protection

description

The TPS771xx and TPS772xx are low-dropout regulators with integrated power-on reset and power good (PG) function respectively. These devices are capable of supplying 150 mA of output current with a dropout of 115 mV (TPS77133, TPS77233). Quiescent current is 92 µA at full load dropping down to 1 μ A when device is disabled. These devices are optimized to be stable with a wide range of output capacitors including low ESR ceramic (10 μ F) or low capacitance (1 μ F) tantalum capacitors. These devices have extremely low noise output performance (55 μ V_{rms}) without using any added filter capacitors. TPS771xx and TPS772xx are designed to have fast transient response for larger load current changes.

The TPS771xx or TPS772xx is offered in 1.5 V,



1.8-V, 2.7-V, 2.8-V, 3.3-V, and 5.0 V fixed-voltage versions and in an adjustable version (programmable over the range of 1.5 V to 5.5 V). Output voltage tolerance is 2% over line, load, and temperature ranges. The TPS771xx and TPS772xx families are available in 8-pin MSOP (DGK) packages.

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 115 mV at an output current of 150 mA for 3.3 volt option) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (typically 92 μ A over the full range of output current, 0 mA to 150 mA). These two key specifications yield a significant improvement in operating life for battery-powered systems.



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description (continued)

The device is enabled when the EN pin is connected to a low-level input voltage. This LDO family also features a sleep mode; applying a TTL high signal to EN (enable) shuts down the regulator, reducing the quiescent current to less than 1 μ A at T_J = 25°C.

The TPS771xx features an integrated power-on reset, commonly used as a supply voltage supervisor (SVS) or reset output voltage. The RESET output of the TPS771xx initiates a reset in DSP, microcomputer or microprocessor systems at power up and in the event of an undervoltage condition. An internal comparator in the TPS771xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage. When OUT reaches 95% of its regulated voltage, RESET will go to a high-impedance state after a 220 ms delay. RESET will go to low-impedance state when OUT is pulled below 95% (i.e. over load condition) of its regulated voltage.

For the TPS772xx, the power good terminal (PG) is an active high output, which can be used to implement a power-on reset or a low-battery indicator. An internal comparator in the TPS772xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage. When OUT falls below 82% of its regulated voltage, PG will go to a low-impedance state. PG will go to a high-impedance state when OUT is above 82% of its regulated voltage.

| - | OUTPUT VOLTAGE (V) | | | D DEVICES (DGK) | |
|----------------|------------------------------|-------------|--------------------|--------------------|--------------------|
| Тյ | ТҮР | | TPS771xx SYMBOL | | TPS772xx SYMBOL |
| | 5.0 | TPS77150DGK | AFV | TPS77250DGK | AGE |
| | 3.3 | TPS77133DGK | AFU | TPS77233DGK | AGD |
| | 2.8 | TPS77128DGK | AFS | TPS77228DGK | AGB |
| -40°C to 125°C | 2.7 | TPS77127DGK | AFR | TPS77227DGK | AGA |
| 40 0 10 123 0 | 1.8 | TPS77118DGK | AFP | TPS77218DGK | AFY |
| | 1.5 | TPS77115DGK | AFO | TPS77215DGK | AFX |
| | Adjustable 1.5 V to 5.5 V | TPS77101DGK | AFN | TPS77201DGK | AFW |

AVAILABLE OPTIONS

NOTE: The TPS77101 and TPS77201 are programmable using an external resistor divider (see application information). The DGK package is available taped and reeled. Add an R suffix to the device type (e.g., TPS77101DGKR).

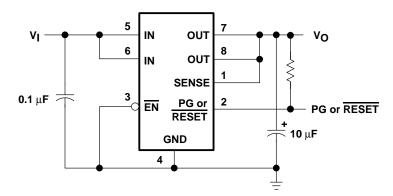
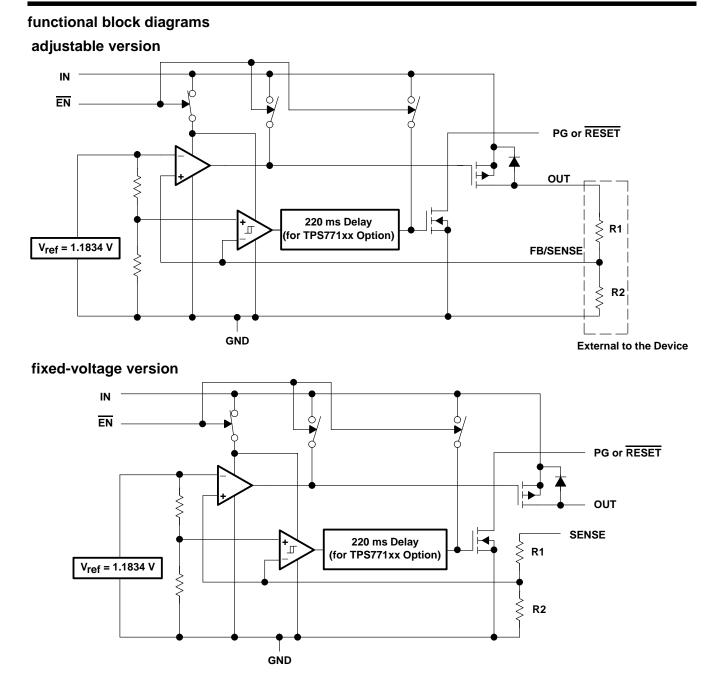


Figure 1. Typical Application Configuration (For Fixed Output Options)



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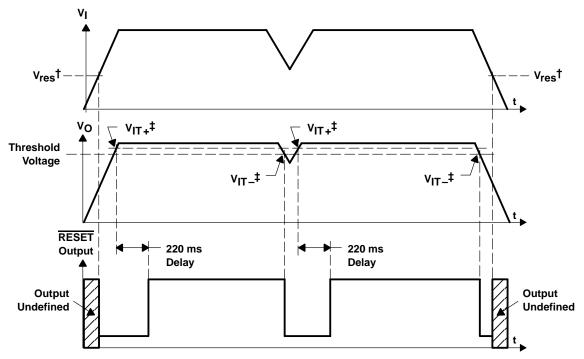


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Terminal Functions

| TERMIN | IAL | | DECODIDENCI |
|----------|------|-----|--|
| NAME | NO. | 1/0 | DESCRIPTION |
| TPS771XX | | | |
| FB/SENSE | 1 | Ι | Feedback input voltage for adjustable device (sense input for fixed options) |
| RESET | 2 | 0 | Reset output |
| EN | 3 | Ι | Enable input |
| GND | 4 | | Regulator ground |
| IN | 5, 6 | I | Input voltage |
| OUT | 7, 8 | 0 | Regulated output voltage |
| TPS772XX | | | |
| FB/SENSE | 1 | Ι | Feedback input voltage for adjustable device (sense input for fixed options) |
| PG | 2 | 0 | Power good |
| EN | 3 | Ι | Enable input |
| GND | 4 | | Regulator ground |
| IN | 5, 6 | Ι | Input voltage |
| OUT | 7, 8 | 0 | Regulated output voltage |

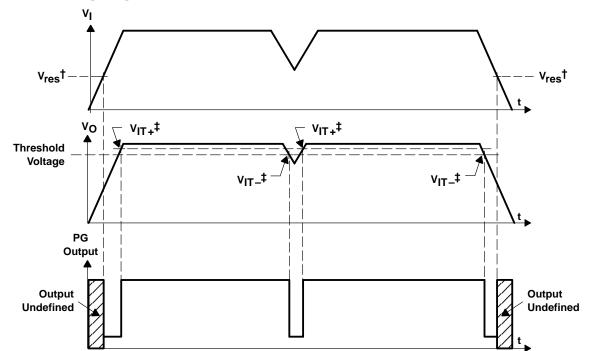
TPS771xx RESET timing diagram



[†] V_{res} is the minimum input voltage for a valid RESET. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology. [‡] V_{IT} – Trip voltage is typically 5% lower than the output voltage (95%V_O) V_{IT-} to V_{IT+} is the hysteresis voltage.



TPS772xx PG timing diagram



[†] V_{res} is the minimum input voltage for a valid PG. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology.

[‡]V_{IT} – Trip voltage is typically 18% lower than the output voltage (82%V_O) V_{IT} to V_{IT} + is the hysteresis voltage.

absolute maximum ratings over operating junction temperature range (unless otherwise noted)[†]

| Input voltage range, V _I , (see Note 1) | –0.3 V to 13.5 V |
|--|------------------------------|
| Voltage range at EN | –0.3 V to 16.5 V |
| Maximum RESET voltage (TPS771xx) | 16.5 V |
| Maximum PG voltage (TPS772xx) | 16.5 V |
| Peak output current | Internally limited |
| | |
| Continuous total power dissipation | See Dissipation Rating Table |
| Continuous total power dissipation Output voltage, V _O (OUT, FB) | |
| | 5.5 V |
| Output voltage, V _O (OUT, FB) | 5.5 V –40°C to 125°C |

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: All voltage values are with respect to network terminal ground.



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| | DISSIPATION RATING TABLE – FREE-AIR TEMPERATURES | | | | | | | | | | | | | |
|---|--|-------|------|--------|------------|--------|--------|--|--|--|--|--|--|--|
| PACKAGEAIR FLOW (CFM) θ_{JA} (°C/W) θ_{JC} (°C/W) $T_A < 25^{\circ}$ CDERATING FACTOR DERATING $T_A = 70^{\circ}$ C $T_A = 85^{\circ}$ C(°C/W)(°C/W)(°C/W)POWER RATINGABOVE T_A = 25^{\circ}CPOWER RATINGPOWER RATING | | | | | | | | | | | | | | |
| | 0 | 266.2 | 3.84 | 376 mW | 3.76 mW/°C | 207 mW | 150 mW | | | | | | | |
| DGK | 150 | 255.2 | 3.92 | 392 mW | 3.92 mW/°C | 216 mW | 157 mW | | | | | | | |
| | 250 | 242.8 | 4.21 | 412 mW | 4.12 mW/°C | 227 mW | 165 mW | | | | | | | |

recommended operating conditions

| | MIN | MAX | UNIT |
|---|-----|-----|------|
| Input voltage, VI [†] | 2.7 | 10 | V |
| Output voltage range, VO | 1.5 | 5.5 | V |
| Output current, I _O (see Note 2) | 0 | 150 | mA |
| Operating virtual junction temperature, T _J (see Note 2) | -40 | 125 | °C |

[†] To calculate the minimum input voltage for your maximum output current, use the following equation: V_{I(min)} = V_{O(max)} + V_{DO(max load)}. NOTE 2: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.



electrical characteristics over recommended operating junction temperature range (–40°C to 125°C), $V_I = V_{O(typ)} + 1 V$, $I_O = 1 \text{ mA}$, $\overline{EN} = 0 V$, $C_O = 10 \mu F$ (unless otherwise noted)

| PARAM | IETER | TEST C | ONDITIONS | MIN | TYP | MAX | UNIT | | |
|---------------------------------------|---|--|--------------------------------|--------|-------|--------|-------|--|--|
| | | $1.5 \text{ V} \le \text{V}_{O} \le 5.5 \text{ V},$ | TJ = 25°C | | VO | | | | |
| | Adjustable voltage | $1.5~V \leq V_O \leq 5.5~V$ | | 0.98VO | | 1.02VO | V | | |
| | | TJ = 25°C, | 2.7 V < V _{IN} < 10 V | | 1.5 | | | | |
| | 1.5-V Output | $2.7 \text{ V} < \text{V}_{IN} < 10 \text{ V}$ | | 1.470 | | 1.530 | | | |
| | | $T_J = 25^{\circ}C$, | 2.8 V < V _{IN} < 10 V | | 1.8 | | | | |
| | 1.8-V Output | $2.8 \text{ V} < \text{V}_{IN} < 10 \text{ V}$ | | 1.764 | | 1.836 | | | |
| Output voltage (see Notes 3 and 4) | 2.7-V Output | $T_J = 25^{\circ}C$, | 3.7 V < V _{IN} < 10 V | | 2.7 | | v | | |
| | 2.7-0 Output | $3.7 \text{ V} < \text{V}_{IN} < 10 \text{ V}$ | | 2.646 | | 2.754 | v | | |
| | 2.8-V Output | T _J = 25°C, | 3.8 V < V _{IN} < 10 V | | 2.8 | | | | |
| | 2.0-0 Output | 3.8 V < V _{IN} < 10 V | | 2.744 | | 2.856 | | | |
| | 3.3-V Output | T _J = 25°C, | 4.3 V < V _{IN} < 10 V | | 3.3 | | | | |
| | | $4.3 \text{ V} < \text{V}_{IN} < 10 \text{ V}$ | | 3.234 | | 3.366 | | | |
| | 5.0-V Output | T _J = 25°C, | 6 V < V _{IN} < 10 V | | 5.0 | | v | | |
| | 5.0-V Output | 6 V < V _{IN} < 10 V T _{.I} = 25°C | | 4.900 | | 5.100 | v | | |
| Quiescent current (GND cu | ent current (GND current) (see Notes 3 and 4) | | | | 92 | | μA | | |
| | | | | | | 125 | μΛ | | |
| Output voltage line regulation | $(\Lambda V \cap N \cap)$ (see Note 5) | V_{O} + 1 V < $V_{I} \le 10 V$ | | | 0.005 | | %/V | | |
| output voltage into regulatio | | $V_{O} + 1 V < V_{I} \le 10 V$ | | | | 0.05 | %/V | | |
| Load regulation | | $T_J = 25^{\circ}C$ | | | 1 | | mV | | |
| Output noise voltage | | BW = 300 Hz to 100 TPS77118, TPS7721 | | | 55 | | μVrms | | |
| Output current Limit | | $V_{O} = 0 V$ | | | 0.9 | 1.3 | А | | |
| Peak output current | | 2 ms pulse width, | 50% duty cycle | | 400 | | mA | | |
| Thermal shutdown junction | temperature | | | | 144 | | °C | | |
| Standby ourrant | | $\overline{EN} = V_{I},$ | TJ = 25°C | | | 1 | μΑ | | |
| Standby current | | $\overline{EN} = V_{I}$ | | | | 3 | μA | | |
| FB input current | Adjustable voltage | FB = 1.5 V | | | | 1 | μΑ | | |
| High level enable input volta | age | | | 2 | | | V | | |
| Low level enable input volta | age | | | | | 0.7 | V | | |
| Enable input current | | | | -1 | | 1 | μA | | |
| Power supply ripple rejection | on (TPS77118, TPS77218) | f = 1 KHz, | TJ = 25°C | | 55 | | dB | | |

NOTES: 3. Minimum input operating voltage is 2.7 V or V_{O(typ)} + 1 V, whichever is greater. Maximum input voltage = 10 V, minimum output current 1 mA.

4. If $V_O < 1.8$ V then $V_{I(max)} = 10$ V, $V_{I(min)} = 2.7$ V:

Line regulation (mV) = $(\%/V) \times \frac{V_O(V_{I(max)} - 2.7 V)}{100} \times 1000$

If $V_O > 2.5 \text{ V}$ then $V_{I(max)} = 10 \text{ V}$, $V_{I(min)} = V_O + 1 \text{ V}$:

Line regulation (mV) = $(\%/V) \times \frac{V_O(V_{I(max)} - (V_O + 1))}{100} \times 1000$



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electrical characteristics over recommended operating junction temperature range (-40°C to 125°C), $V_I = V_{O(tvp)} + 1 V$, $I_O = 1 \text{ mA}$, $\overline{EN} = 0 V$, $C_O = 10 \mu F$ (unless otherwise noted) (continued)

| | PARAMETER | | TEST C | ONDITIONS | MIN | TYP | MAX | UNIT |
|------------------------|---------------------------------|---------------|--|-----------------------|------|------|-----|------|
| | Minimum input voltage for valid | PG | I(PG) = 300μA | V(PG) ≤ 0.8 V | | 1.1 | | V |
| Trip threshold voltage | | | VO decreasing | | 79 | | 85 | %VO |
| PG (TPS772xx) | Hysteresis voltage | | Measured at VO | | | 0.5 | | %VO |
| Output low voltage | | VI = 2.7 V, | l _(PG) = 1mA | | 0.15 | 0.4 | V | |
| | Leakage current | | V(PG) = 5 V | | | | 1 | μΑ |
| | Minimum input voltage for valid | RESET | $I_{(RESET)} = 300$ | μΑ | | 1.1 | | |
| | Trip threshold voltage | | V_{O} decreasing | 92 | | 98 | %VO | |
| Reset | Hysteresis voltage | | Measured at VO | | | 0.5 | | %VO |
| (TPS771xx) | Output low voltage | | VI = 2.7 V, | I(RESET) = 1 mA | | 0.15 | 0.4 | V |
| | Leakage current | | V(RESET) = 5 V | | | | 1 | μΑ |
| | RESET time-out delay | | | | | 220 | | ms |
| | | | I _O = 150 mA, | T _J = 25°C | | 150 | | |
| | | 2.8-V Output | I _O = 150 mA, | | | | 265 | |
| | | | I _O = 150 mA, | $T_J = 25^{\circ}C$ | | 115 | | |
| VDO | Dropout voltage (see Note 6) | 3.3-V Output | I _O = 150 mA | | | 200 | mV | |
| | | E 0 V Outrout | I _O = 150 mA, T _J = 25°C | | | 75 | | |
| | | 5.0-V Output | I _O = 150 mA | | | | 115 | |

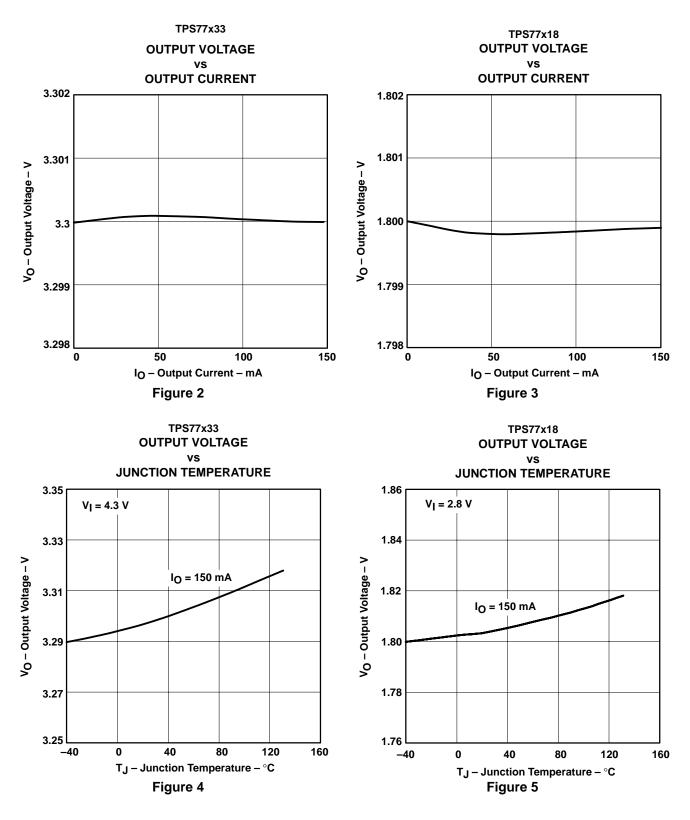
NOTE 6: IN voltage equals V_O(typ) - 100 mV; 1.5 V, 1.8 V, and 2.7 V dropout voltage limited by input voltage range limitations (i.e., 3.3 V input voltage needs to drop to 3.2 V for purpose of this test).

TYPICAL CHARACTERISTICS

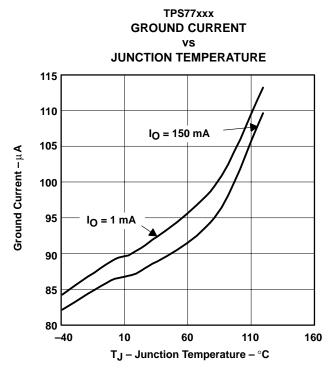
Table of Graphs

| | | | FIGURE |
|-----|------------------------------------|-------------------------|---------|
| ., | | vs Output current | 2, 3 |
| VO | Output voltage | vs Junction temperature | 4, 5 |
| | Ground current | vs Junction temperature | 6 |
| | Power supply rejection ratio | vs Frequency | 7 |
| | Output spectral noise density | vs Frequency | 8 |
| Zo | Output impedance | vs Frequency | 9 |
| ., | | vs Input voltage | 10 |
| VDO | Dropout voltage | vs Junction temperature | 11 |
| | Line transient response | | 12, 14 |
| | Load transient response | | 13, 15 |
| | Output voltage and enable pulse | vs Time | 16 |
| | Equivalent series resistance (ESR) | vs Output current | 18 – 21 |

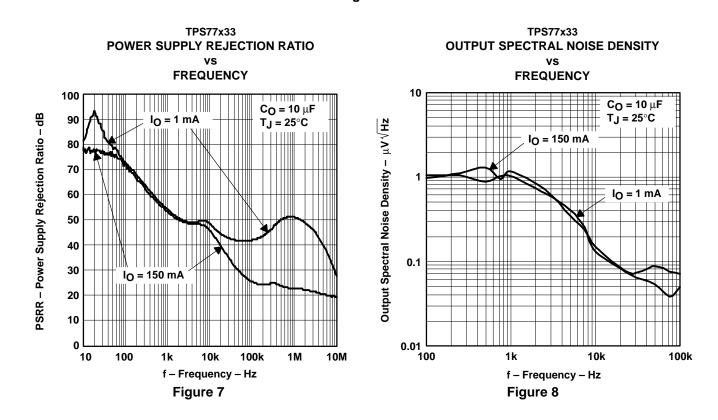




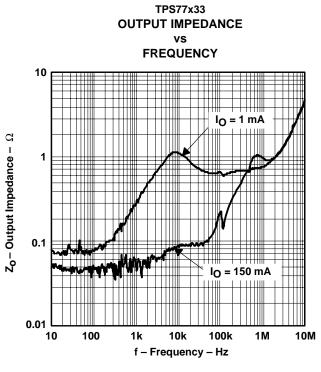




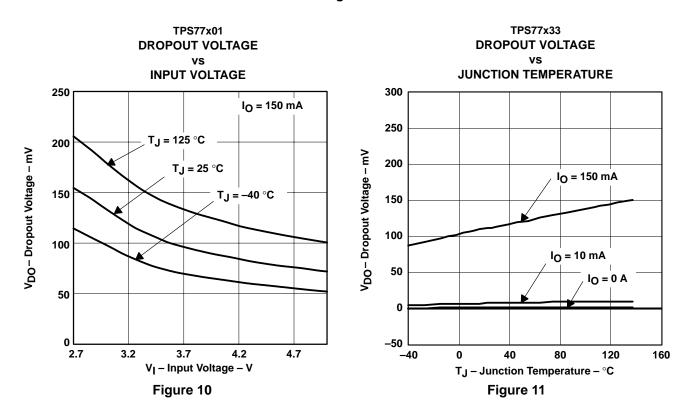




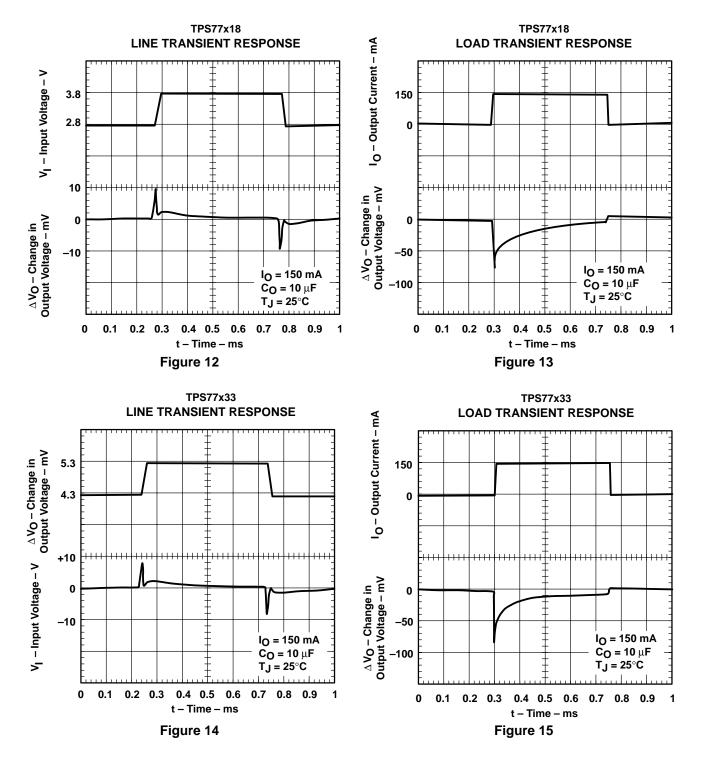






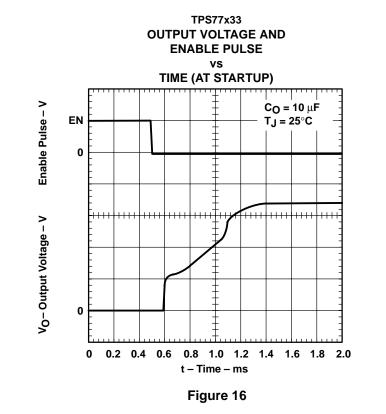












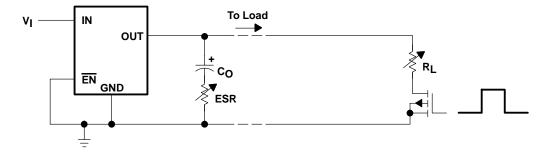
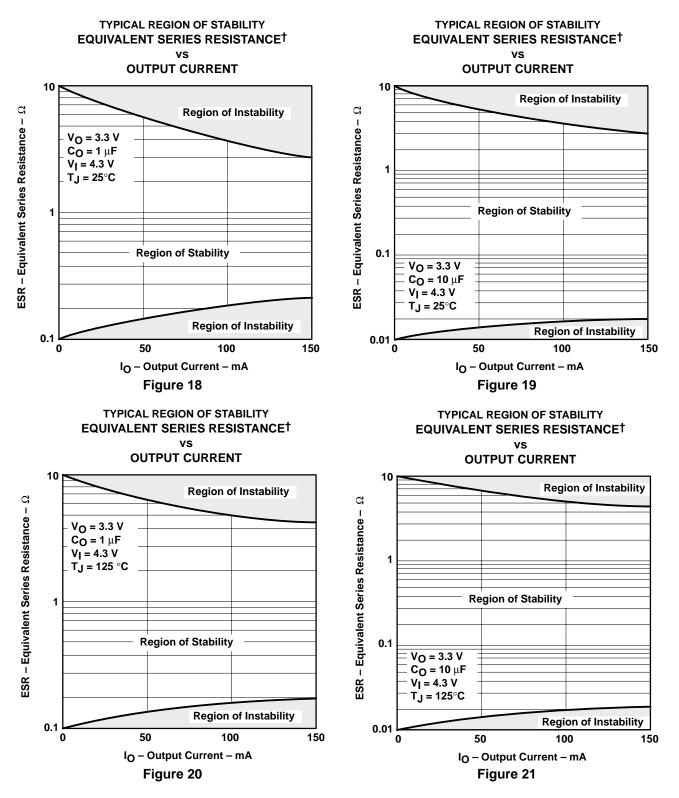


Figure 17. Test Circuit for Typical Regions of Stability (Figures 18 through 21) (Fixed Output Options)



TYPICAL CHARACTERISTICS



[†] Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.



APPLICATION INFORMATION

pin functions

enable (EN)

The EN terminal is an input which enables or shuts down the device. If EN is a logic high, the device will be in shutdown mode. When EN goes to logic low, then the device will be enabled.

power good (PG) (TPS772xx)

The PG terminal is an open drain, active high output that indicates the status of V_{out} (output of the LDO). When V_{out} reaches 82% of the regulated voltage, PG will go to a high-impedance state. It will go to a low-impedance state when V_{out} falls below 82% (i.e. over load condition) of the regulated voltage. The open drain output of the PG terminal requires a pullup resistor.

sense (SENSE)

The SENSE terminal of the fixed-output options must be connected to the regulator output, and the connection should be as short as possible. Internally, SENSE connects to a high-impedance wide-bandwidth amplifier through a resistor-divider network and noise pickup feeds through to the regulator output. It is essential to route the SENSE connection in such a way to minimize/avoid noise pickup. Adding RC networks between the SENSE terminal and V_{out} to filter noise is not recommended because it may cause the regulator to oscillate.

feedback (FB)

FB is an input terminal used for the adjustable-output options and must be connected to an external feedback resistor divider. The FB connection should be as short as possible. It is essential to route it in such a way to minimize/avoid noise pickup. Adding RC networks between FB terminal and V_{out} to filter noise is not recommended because it may cause the regulator to oscillate.

reset (RESET) (TPS771xx)

The RESET terminal is an open drain, active low output that indicates the status of V_{out} . When V_{out} reaches 95% of the regulated voltage, RESET will go to a high-impedance state after a 220-ms delay. RESET will go to a low-impedance state when V_{out} is below 95% of the regulated voltage. The open-drain output of the RESET terminal requires a pullup resistor.



APPLICATION INFORMATION

external capacitor requirements

An input capacitor is not usually required; however, a bypass capacitor (0.047 μ F or larger) improves load transient response and noise rejection if the TPS771xx or TPS772xx is located more than a few inches from the power supply. A higher-capacitance capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Most low noise LDOs require an external capacitor to further reduce noise. This will impact the cost and board space. The TPS771xx and TPS772xx have very low noise specification requirements without using any external components.

Like all low dropout regulators, the TPS771xx or TPS772xx requires an output capacitor connected between OUT (output of the LDO) and GND (signal ground) to stabilize the internal control loop. The minimum recommended capacitance value is 1 μ F provided the ESR meets the requirement in Figures 19 and 21. In addition, a low-ESR capacitor can be used if the capacitance is at least 10 μ F and the ESR meets the requirements in Figures 18 and 20. Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described previously.

Ceramic capacitors have different types of dielectric material with each exhibiting different temperature and voltage variation. The most common types are X5R, X7R, Y5U, Z5U, and NPO. The NPO type ceramic type capacitors are generally the most stable over temperature. However, the X5R and X7R are also relatively stable over temperature (with the X7R being the more stable of the two) and are therefore acceptable to use. The Y5U and Z5U types provide high capacitance in a small geometry, but exhibit large variations over temperature; therefore, the Y5U and Z5U are not generally recommended for use on this LDO. Independent of which type of capacitor is used, one must make certain that at the worst case condition the capacitance/ESR meets the requirement specified in Figures 18 - 21.



APPLICATION INFORMATION

Figure 22 shows the output capacitor and its parasitic impedances in a typical LDO output stage.

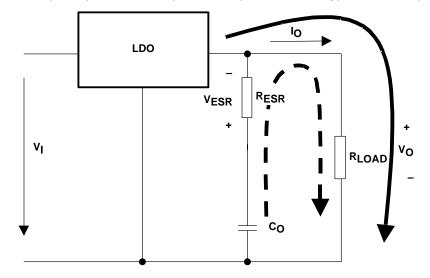


Figure 22. LDO Output Stage With Parasitic Resistances ESR and ESL

In steady state (dc state condition), the load current is supplied by the LDO (solid arrow) and the voltage across the capacitor is the same as the output voltage (V_{Cout} = V_{out}). This means no current is flowing into the C_{out} branch. If Iout suddenly increases (transient condition), the following occurs:

- The LDO is not able to supply the sudden current need due to its response time (t₁ in Figure 23). Therefore, capacitor Cout provides the current for the new load condition (dashed arrow). Cout now acts like a battery with an internal resistance, ESR. Depending on the current demand at the output, a voltage drop will occur at R_{ESR}. This voltage is shown as V_{ESR} in Figure 22.
- When C_{out} is conducting current to the load, initial voltage at the load will be $V_{out} = V_{Cout} V_{ESR}$. Due to the discharge of Cout, the output voltage Vout will drop continuously until the response time t1 of the LDO is reached and the LDO will resume supplying the load. From this point, the output voltage starts rising again until it reaches the regulated voltage. This period is shown as t₂ in Figure 23.

The figure also shows the impact of different ESRs on the output voltage. The left brackets show different levels of ESRs where number 1 displays the lowest and number 3 displays the highest ESR.

From above, the following conclusions can be drawn:

- The higher the ESR, the larger the droop at the beginning of load transient.
- The smaller the output capacitor, the faster the discharge time and the bigger the voltage droop during the LDO response period.



APPLICATION INFORMATION

conclusion

To minimize the transient output droop, capacitors must have a low ESR and be large enough to support the minimum output voltage requirement.

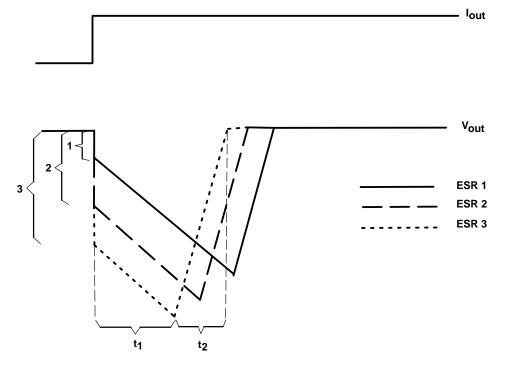


Figure 23. Correlation of Different ESRs and Their Influence to the Regulation of V_{out} at a Load Step From Low-to-High Output Current



APPLICATION INFORMATION

programming the TPS77x01 adjustable LDO regulator

The output voltage of the TPS77x01 adjustable regulator is programmed using an external resistor divider as shown in Figure 24. The output voltage is calculated using:

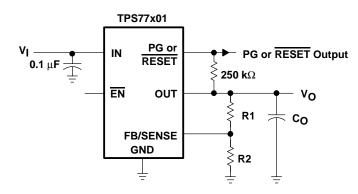
$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right)$$
(1)

Where:

 $V_{ref} = 1.1834 V$ typ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 50- μ A divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided, as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 30.1 k Ω to set the divider current at 50 μ A and then calculate R1 using:

$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2$$
(2)



OUTPUT VOLTAGE PROGRAMMING GUIDE

| OUTPUT VOLTAGE | R1 | R2 | UNIT |
|-------------------|------|------|------|
| 2.5 V | 33.5 | 30.1 | kΩ |
| 3.3 V | 53.8 | 30.1 | kΩ |
| 3.6 V | 61.5 | 30.1 | kΩ |

NOTE: To reduce noise and prevent oscillation, R1 and R2 need to be as close as possible to the FB/SENSE terminal.

Figure 24. TPS77x01 Adjustable LDO Regulator Programming



APPLICATION INFORMATION

regulator protection

The TPS771xx or TPS772xx PMOS-pass transistor has a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS771xx or TPS772xx also features internal current limiting and thermal protection. During normal operation, the TPS771xx or TPS772xx limits output current to approximately 0.9 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_{D} , which must be less than or equal to $P_{D(max)}$.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{J}max - T_{A}}{R_{\theta JA}}$$

Where:

T_Jmax is the maximum allowable junction temperature.

 $R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package, i.e., 266.2°C/W for the 8-terminal MSOP with no airflow.

 T_A is the ambient temperature.

The regulator dissipation is calculated using:

$$\mathsf{P}_{\mathsf{D}} = \left(\mathsf{V}_{\mathsf{I}} - \mathsf{V}_{\mathsf{O}}\right) \times \mathsf{I}_{\mathsf{O}}$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.





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PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|-----------------------------------|----------------------------|---------------------------|--------------|----------------|---------|
| TPS77101DGK | (1) ACTIVE | VSSOP | DGK | 8 | 80 | (2) Green (RoHS & no Sb/Br) | (6) CU NIPDAU | (3) Level-1-260C-UNLIM | -40 to 125 | (4/5) AFN | Samples |
| TPS77101DGKG4 | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFN | Samples |
| TPS77101DGKR | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFN | Samples |
| TPS77101DGKRG4 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFN | Samples |
| TPS77115DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFO | Samples |
| TPS77115DGKR | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFO | Samples |
| TPS77118DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFP | Samples |
| TPS77118DGKG4 | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFP | Samples |
| TPS77127DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFR | Samples |
| TPS77128DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFS | Samples |
| TPS77128DGKG4 | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFS | Samples |
| TPS77133DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU CU NIPDAUAG | Level-1-260C-UNLIM | -40 to 125 | AFU | Samples |
| TPS77133DGKG4 | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFU | Samples |
| TPS77133DGKR | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU CU NIPDAUAG | Level-1-260C-UNLIM | -40 to 125 | AFU | Samples |
| TPS77133DGKRG4 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFU | Samples |
| TPS77150DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFV | Samples |
| TPS77150DGKG4 | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFV | Samples |



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| Orderable Device | Status | Package Type | Package | Pins | Package | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|--------|--------------|---------|------|---------|----------------------------|------------------|--------------------|--------------|----------------|---------|
| | (1) | | Drawing | | Qty | (2) | (6) | (3) | | (4/5) | |
| TPS77150DGKR | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFV | Samples |
| TPS77201DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFW | Samples |
| TPS77218DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AFY | Samples |
| TPS77227DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AGA | Samples |
| TPS77233DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AGD | Samples |
| TPS77233DGKG4 | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AGD | Samples |
| TPS77250DGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AGE | Samples |
| TPS77250DGKG4 | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AGE | Samples |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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PACKAGE OPTION ADDENDUM

11-Sep-2016

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| *All dimensions are nominal Device | 1 | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--|-------|--------------------|---|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| TPS77101DGKR | VSSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| TPS77115DGKR | VSSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| TPS77133DGKR | VSSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| TPS77150DGKR | VSSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

10-Aug-2016



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS77101DGKR | VSSOP | DGK | 8 | 2500 | 358.0 | 335.0 | 35.0 |
| TPS77115DGKR | VSSOP | DGK | 8 | 2500 | 358.0 | 335.0 | 35.0 |
| TPS77133DGKR | VSSOP | DGK | 8 | 2500 | 358.0 | 335.0 | 35.0 |
| TPS77150DGKR | VSSOP | DGK | 8 | 2500 | 358.0 | 335.0 | 35.0 |

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